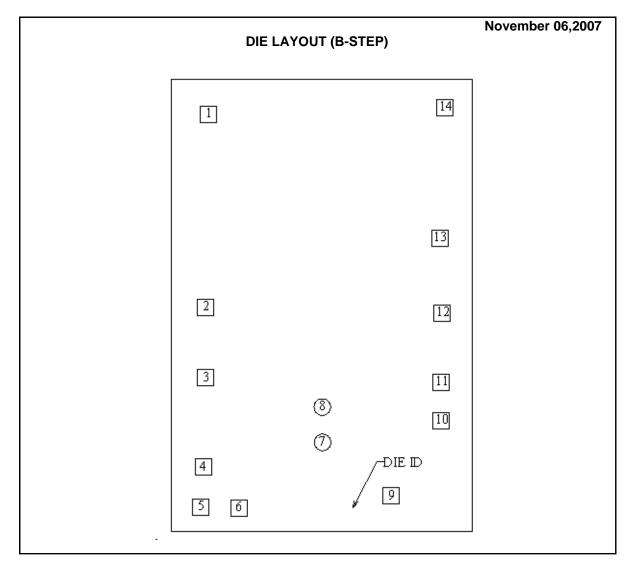


LP2953 MDS MCD1420A ADJUSTABLE MICROPOWER LOW-DROPOUT VOLTAGE REGULATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information		
Physical Die Identification	LP2952B	Bond Pad Opening Size (min)	90µm x 90µm	
Die Step	В	Bond Pad Metalization	ALUMINUM	
Physi	Physical Attributes		VOM NITRIDE	
Wafer Diameter	150mm	Back Side Metal	BARE BACK	
Die Size (Drawn)	1651μm x 2489μm 65.0mils x 98.0mils	Back Side Connection	GND	
Thickness	305µm Nominal			
Min Pitch	209µm Nominal			

Special Assembly Requirements: Note: Actual die size is rounded to the nearest micron.



The Sight & Sound of Information

LP2953 MDS MCD1420A

ADJUSTABLE MICROPOWER LOW-DROPOUT VOLTAGE REGULATOR

	Die Bond Pa	d Coordina	ate Locations	(B-Step)		
(Referenced to	(Referenced to die center, coordinates in μ m) NC = No Connection, N.U. = Not Used					
SIGNAL	PAD#	X/Y (S	PAD SIZE		
NAME	NUMBER	X	Y (>	(Υ
OUTPUT	1	-623	1055	90	х	90
SENSE	2	-640	-10	90	х	90
SHUTDOWN	3	-640	-399	90	х	90
ERROR	4	-653	-890	90	х	90
NC	5	-666	-1110	90	x	90
GND	6	-456	-1115	90	х	90
NC	7	4	-753	91	x	90
NC	8	4	-560	91	x	91
COMP OUT	9	382	-1049	90	х	90
COMP INPUT	10	658	-633	90	х	90
REFERENCE	11	658	-424	90	х	90
VTAP	12	663	-43	90	х	90
FEEDBACK	13	649	372	90	х	90
INPUT	14	678	1089	90	х	90



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